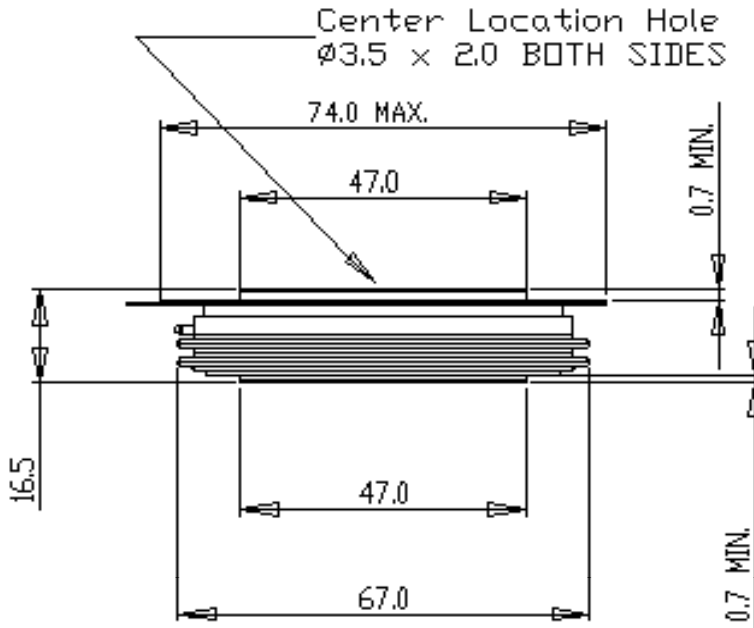




The T9S0 SCR employs a Center-Fired amplifying gate structure which allows the SCR to be reliably operated at high di/dt and high dv/dt conditions in phase control applications.

FEATURES:

- Low On-State Voltage
- High di/dt Capability
- High dv/dt Capability
- Hermetic Ceramic Package
- Excellent Surge and I^2t Ratings

APPLICATIONS:

- DC Power Supplies
- Plating Supplies
- Welding Supplies

ORDERING INFORMATION

Select the complete 12 digit Part Number using the table below.
EXAMPLE: **T9S0182003DH** is an 1800V-1500A SCR with 200ma IGT and 12 inch gate and cathode potential leads.

PART	Voltage Rating $V_{DRM}-V_{RRM}$	Voltage Code	Current Rating I_{tavg}	Current Code	Turn-Off T_q	Gate I_{GT}	Leads
T9S0	1200V	12	2000A	20	0	3	DH
	1400V	14					
	1600V	16			400us typ.	200ma	12"
	1800V	18					

Revised: 5/5/2008

Absolute Maximum Ratings

Characteristic	Symbol	Rating	Units
Repetitive Peak Voltage	$V_{DRM}-V_{RRM}$	1800	Volts
Average On-State Current, $T_C=72^{\circ}C$	$I_{T(Avg.)}$	2000	A
RMS On-State Current, $T_C=72^{\circ}C$	$I_{T(RMS)}$	3142	A
Average On-State Current, $T_C=55^{\circ}C$	$I_{T(Avg.)}$	2200	A
RMS On-State Current, $T_C=55^{\circ}C$	$I_{T(RMS)}$	3456	A
Peak One Cycle Surge Current, 60Hz, $V_R=0V$	I_{TSM}	27,000	A
Peak One Cycle Surge Current, 50Hz, $V_R=0V$	I_{TSM}	25,456	A
Fuse Coordination I^2t , 60Hz	I^2t	3.04E+06	A ² s
Fuse Coordination I^2t , 50Hz	I^2t	3.24E+06	A ² s
Critical Rate-of-Rise of On-State Current Repetitive	di/dt	100	A/us
Critical Rate-of-Rise of On-State Current Non-Repetitive	di/dt	200	A/us
Critical Rate-of-Rise of Off-State Voltage $V_D = \frac{2}{3} \cdot V_{DRM}$	dv/dt	1000	V/us
Peak Gate Power, 100us	P_{GM}	16	Watts
Average Gate Power	$P_{G(avg)}$	5	Watts
Operating Temperature	T_j	-20 to +125	$^{\circ}C$
Storage Temperature	$T_{Stg.}$	-50 to +150	$^{\circ}C$
Approximate Weight		0.65	lb
		0.29	Kg
Mounting Force		5500-6000	lbs
		24.5 - 26.7	Knewtons

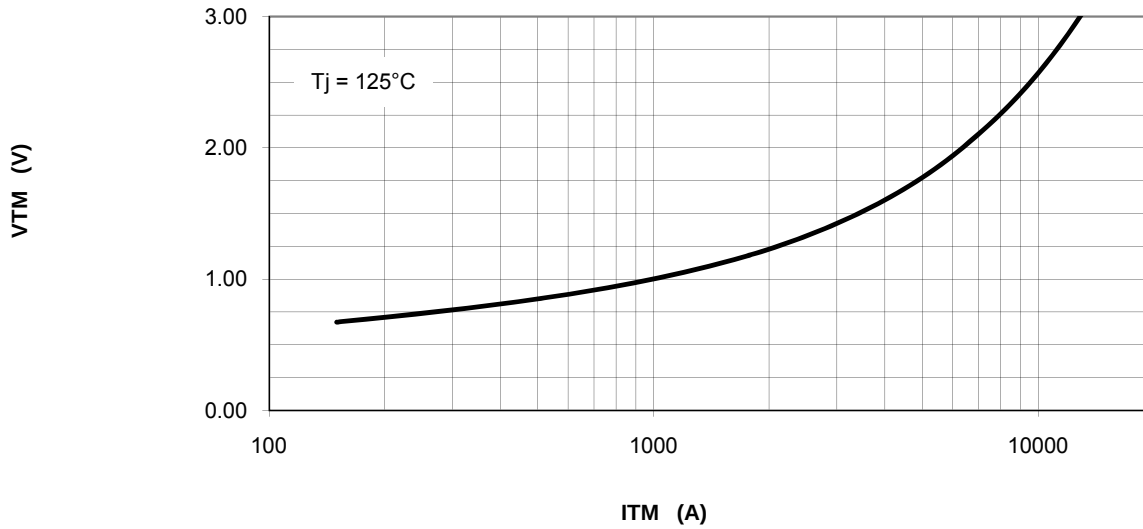
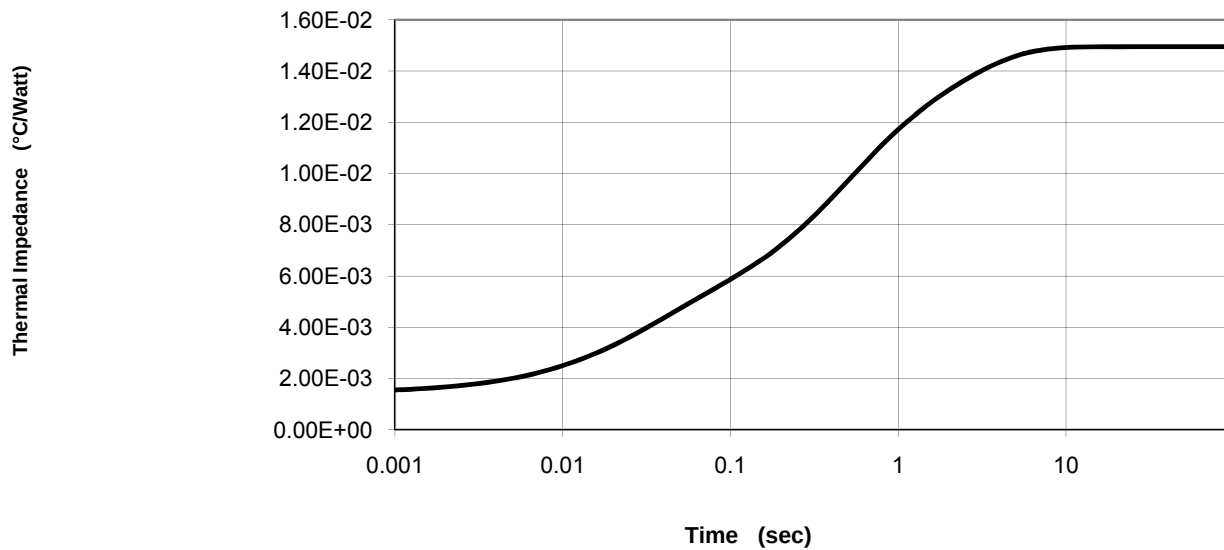
Information presented is based upon limited testing or projected capabilities. This information is subject to change without notice. The manufacturer makes no claim as to suitability for use, reliability, capability or future availability of this product.

Electrical Characteristics, $T_j=25^\circ\text{C}$ unless otherwise specified

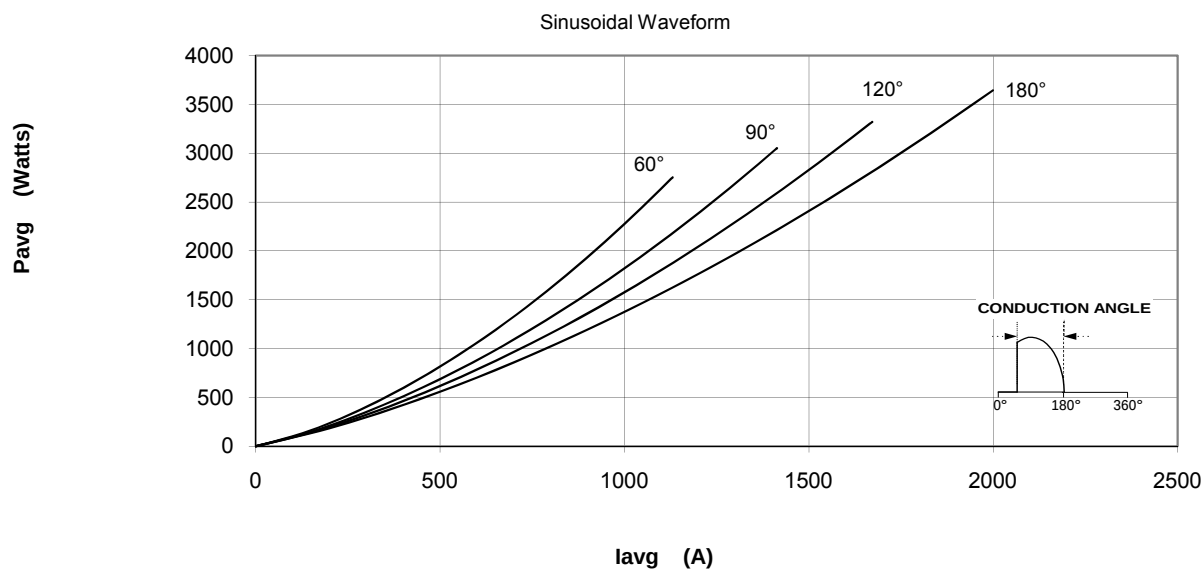
Characteristic	Symbol	Test Conditions	Rating			Units
			min	typ	max	
Repetitive Peak Leakage Current	$I_{\text{DRM}}/I_{\text{RRM}}$	$T_j=125^\circ\text{C}$, $V_{\text{DRM}}=\text{Rated}$			150	ma
Peak On-State Voltage	V_{TM}	$T_j=125^\circ\text{C}$, $I_{\text{TM}}=1500\text{A}$			1.15	V
V_{TM} Model, Low Level	V_0	$T_j=125^\circ\text{C}$			0.755	V
$V_{\text{TM}} = V_0 + r \cdot I_{\text{TM}}$	r	$15\% I_{\text{TM}} - \pi \cdot I_{\text{TM}}$			2.26E-01	m Ω
V_{TM} Model, High Level	V_0	$T_j=125^\circ\text{C}$			1.044	V
$V_{\text{TM}} = V_0 + r \cdot I_{\text{TM}}$	r	$\pi \cdot I_{\text{TM}} - I_{\text{TSM}}$			1.50E-01	m Ω
V_{TM} Model, Hiç 4-Term	A	$T_j=125^\circ\text{C}$			0.200	
$V_{\text{TM}} = A + B \cdot \ln(I_{\text{TM}}) +$	B	$15\% I_{\text{TM}} - I_{\text{TSM}}$			0.083	
$C \cdot (I_{\text{TM}}) + D \cdot (I_{\text{TM}})^{1/2}$	C				1.28E-04	
	D				3.27E-03	
Turn-On Delay Time	t_d	$V_D = 0.5 \cdot V_{\text{DRM}}$ Gate Drive: 40V - 20 Ω		1.5		us
Turn-Off Time	t_q	$T_j=125^\circ\text{C}$ $dv/dt = 20\text{V/us}$ to 80% V_{DRM}		400		us
Gate Trigger Current	I_{GT}	$T_j=25^\circ\text{C}$ $V_D = 12\text{V}$	30	90	200	ma
Gate Trigger Voltage	V_{GT}		0.6	1.6	3.0	V
Peak Reverse Gate Voltage	V_{GRM}				5	V

Thermal Characteristics

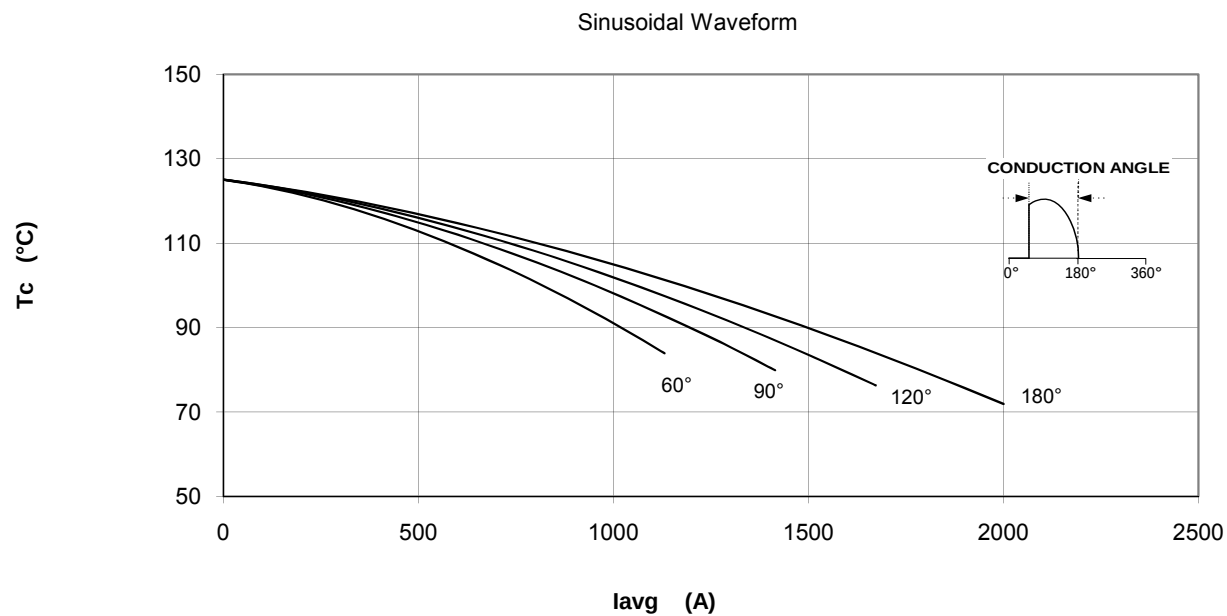
			Rating				
Characteristic	Symbol	Test Conditions	max			Units	
Thermal Resistance							
Junction to Case	$R\Theta_{jc}$	Double side cooled	0.015			°C/Watt	
Case to Sink	$R\Theta_{cs}$	Double side cooled	0.0025			°C/Watt	
Thermal Impedance Model							
$Z\Theta_{jc}$		Double side cooled					
$Z\Theta_{jc}(t) = \Sigma(A(N) \cdot (1 - \exp(-t/Tau(N))))$							
		where:	N =	1	2	3	4
			A(N) =	1.42E-03	2.97E-03	6.07E-03	4.50E-03
			Tau(N) =	5.95E-05	2.76E-02	4.01E-01	2.00E+00

Maximum On-State Voltage Drop**MAXIMUM TRANSIENT THERMAL IMPEDANCE**

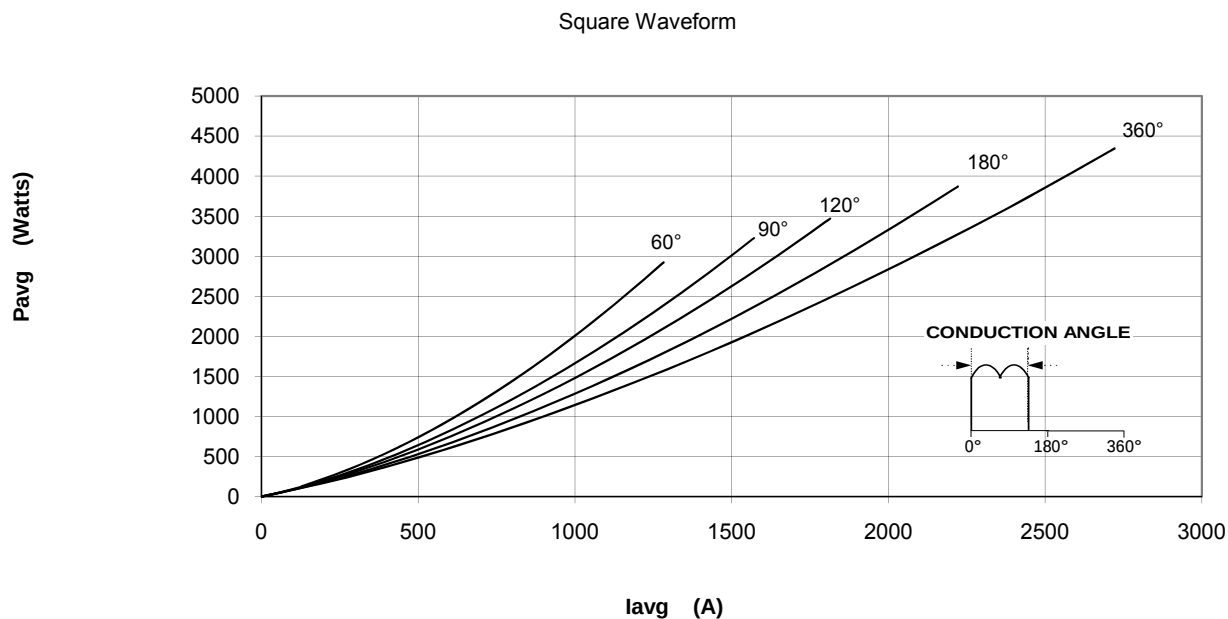
Maximum On-State Power Dissipation



Maximum Allowable Case Temperature



Maximum On-State Power Dissipation



Maximum Allowable Case Temperature

